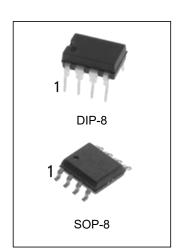


Serial Timekeeper Chip

Features

- Operating voltage: 2.0V~5.5V
- Maximum input serial clock: 500kHz at V_{DD}=2V, 2MHz at V_{DD}=5V
- Operating current: less than 1μA at 2V,less than 1.2μA at 5V
- TTL compatible
 - V_{IH} :2.0 $V \sim V_{DD}$ +0.3V at V_{DD} =5V
 - V_{IL} :0.3V~+0.8V at V_{DD} =5V
- Two data transmission modes: single-byte,or burst mode
- Serial I/O transmission
- All registers store BCD format
- HT1380: 8-pin DIP package
 HT1381: 8-pin SOP package



Applications

- Microcomputer serial clock
- Clock and Calendar

Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
HT1380N	DIP-8	HT1380	TUBE	2000pcs/box
HT1381M/TR	SOP-8	HT1381	REEL	2500pcs/reel

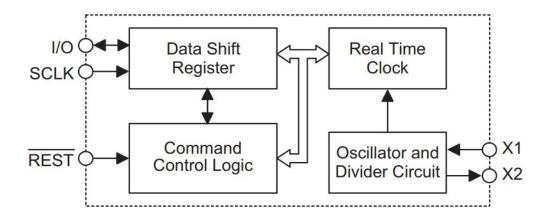


General Description

The HT1380/HT1381 is a serial timekeeper IC which provides seconds, minutes, hours, day, date, month and year information. The number of days in each month and leap years are automatically adjusted. The HT1380/HT1381 is designed for low power consumption and can operate in two modes: one is the 12-hour mode with an AM/PM indicator, the other is the 24-hour mode.

The HT1380/HT1381 has several registers to store the corresponding information with 8-bit data format. A 32768Hz crystal is required to provide the correct tim- ing. In order to minimize the pin number, the HT1380/HT1381 use a serial I/O transmission method to interface with a microprocessor. Only three wires are required: (1) REST (2) SCLK and (3) I/O. Data can be delivered 1 byte at a time or in a burst of up to 8 bytes.

Block Diagram





Pin Assignment



PIN Description

PIN No.	PIN Name	I/O	Internal Connection	Description
1	NC			No internal commection
2	X1	I	CMOS	32768Hz crystal input pad
3	X2	0	CMOS	Oscillator output pad
4	VSS		CMOS	Negative power supply, ground
5	REST	I	CMOS	Reset pin with serial transmission
6	I/O	I/O	CMOS	Data input/output pin with serial transmission
7	SCLK	I	CMOS	Serial clock pulse pin with serial transmission
8	VDD		CMOS	Positive power supply

Absolute Maximum Ratings

Parameter	Min	Max	Unit
Supply Voltage	0.3	5.5	V
Input Voltage	V _{SS} -0.3V	V _{DD} +0.3V	V
Operating Temperature	0	70	°C

Note: These are stress ratings only. Stresses exceeding the range specified under Absolute Maximum Ratings may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.



D.C. Characteristics

(Ta=25℃)

Cymahal	Davamatav	-	Test Conditions	Min	Tim	May	Unit	
Symbol	Parameter	V _{DD}	Conditions	Min.	Тур.	Max.	Ullit	
V_{DD}	Operating Voltage			2		5.5	V	
	Ctondby Cymant	2V				100	nA	
I _{STB}	Standby Current	5V				100	nA	
ı	Operation Comment	2V	Nolocal		0.7	1.0	μΑ	
I _{DD}	Operating Current	5V	5V No load		0.7	1.2	μΑ	
	Course Cumant	2V	V _{OH} =1.8V	0.2	0.4		mA	
Іон	Source Current	5V	V _{OH} =4.5V	0.5	1.0		mA	
ı	Cink Current	2V	V _{OL} =0.2V	0.7	1.5		mA	
IOL	I _{OL} Sink Current	5V	V _{OL} =0.5V	2.0	4.0		mA	
V _{IH}	"H" Input Voltage	5V		2			V	
V _{IL}	"L" Input Voltage	5V				0.8	V	

Note: ISTB is specified with SCLK, I/O, REST open. The clock halt bit must be set to logic 1 (oscillator di sabled).



A.C.Characteristics

(Ta=25℃)

Or mark al	Donomoton.	Test 0	Conditions	NA:	T	Na	I I sa i 4	
Symbol	Parameter	V _{DD}	Conditions	Min.	Тур.	Max.	Unit	
1	Data to Clask Satura	2V		200				
t _{DC}	Data to Clock Setup	5V		50			ns	
t	Clock to Data Hold	2V		280			ne	
t _{CDH}	Clock to Data Hold	5V		70			ns	
t _{CDD}	Clock to Data Delay	2V				800	ns	
CDD	Clock to Data Delay	5V				200	115	
t_CL	Clock Low Time	2V		1000			ns	
ICL.	Clock Low Time	5V		250			115	
t _{CH}	Clock High Time	2V		1000			ns	
CH C	Clock High Time	5V		250			1.0	
f _{SCLK}	Clock Frequency	2V				0.5	MHz	
ISCLK	Glock Frequency	5V				2.0	IVITZ	
tr	Clock Rise and Fall Time	2V				2000	20	
t _f	Clock Nise and Fall Time	5V				500	ns	
tcc	Reset to Clock Setup	2V		4			us	
icc .	Reset to Clock Setup	5V		1			us	
tanı	Clock to Reset Hold	2V		240			ne	
t _{CCH}	Clock to Neset Hold	5V		60			ns	
town	Reset Inactive Time	2V		4			lie.	
t _{CWH}	17696t HIACUVE THIE	5V		1			us	
t	Reset to I/O High Im- pedance	2V			280	no		
t_{CDZ}	Neset to I/O High line pedance	5V				70	ns	



Functional Description

The HT1380/HT1381 mainly contains the following in- ternal elements: a data shift register array to store the clock/calendar data, command control logic, oscillator circuit and read timer clock. The clock is contained in eight read/write registers as shown below. Data con- tained in the clock register is in binary coded decimal format.

Two modes are available for transferring the data be- tween the microprocessor and the HT1380/HT1381. One is in single-byte mode and the other is in multi- ple-byte mode.

The HT1380/HT1381 also contains two additional bits, the clock halt bit (CH) and the write protect bit (WP).

These bits control the operation of the oscillator and so data can be written to the register array. These two bits should first be specified in order to read from and write to the register array properly.

Command Byte

For each data transfer, a Command Byte is initiated to specify which register is accessed. This is to determine whether a read, write, or test cycle is operated and whether a single byte or burst mode transfer is to occur. Refer to the table shown below and follow the steps to write the data to the chip. First give a Command Byte of HT1380/HT1381, and then write a data in the register.

This table illustrates the correlation between Command Byte and their bits:

Function Description		Command Byte									
Function Description	C7	C6	C5	C4	C3	C2	C1	C0			
Select Read or Write Cycle								R/W			
Specify the Register to be Accessed					A2	A1	A0				
Clock Halt Flag	С										
For IC Test Only	1	0	0	1	Х	х	Х	1			
Select Single Byte or Burst Mode	1	0	1	1	1	1	1	Х			

Note: "X" stands for don't care



The following table shows the register address and its data format:

Degister Name	Range			Reg	gister	Defini	tion			Address	Bit R/W	Command			
Register Name	Data	D7	D6	D5	D4	D3	D2	D1	D0	A2~A0	DIL K/VV	Byte			
Seconds	00~59	СН		10 SE	<u></u>		SEC		000	WR	10000000				
Seconds	00~39	51		10 SE			JI			000	VVIX	10000001			
Minutes	00~59	0		10 MIN	NI.		N	IN		001	WR	10000010			
Militates	00-39	0		TO IVIII	`		IVI	IIN		001	VVIX	10000011			
Hours	01~12	12\	0	AP	HR		нС	UR		010	WR	10000100			
Tiours	00~23	24	0	10	HR		110	OIX		010	VVIX	10000101			
Date	01~31						DATE		011	WR	10000110				
Date	01/31	0	0	10 E	ATE		<i>DF</i>	\		011	VVIX	10000111			
Month	01~12						МО	MONTH		100	WR	10001000			
IVIOTITI	0112	0	0	0	10M		IVIO	INIII		100	VVIX	10001001			
Day	01~07						D.	۸٧		101	WR	10001010			
Day	01 07	0	0	0	0		DAY		101	VVIX	10001011				
Year	00~99		10 V	EAR		YEAR				110	WR	10001100			
Teal	00-99		10 1	LAIN						110	VVIX	10001101			
Write Protect	00~80	WP			ALMAYS ZEDO		AVC 7EDO				AVS 7EBO		111	WR	10001110
vviile Flotect	00.300	VVF			_LVV	A13 Z	AYS ZERO			111	VVIX	10001111			

CH: Clock Halt bit

CH=0 oscillator enabled CH=1 oscillator disabled

WP: Write protect bit

WP=0 register data can be written in WP=1 register data can not be written in

Bit 7 of Reg2: 12/24 mode flag

bit 7=1, 12-hour mode bit 7=0, 24-hour mode

Bit 5 of Reg2: AM/PM mode defined

AP=1 PM mode AP=0 AM mode

R/W Signal

The LSB of the Command Byte determines whether thedata in the register be read or be written to. When it is set as "0" means that a write cycle is to take place otherwise this chip will be set into the read mode.

A0~A2

A0 to A2 of the Command Byte is used to specify which registers are to be accessed. There are eight registers used to control the month data, etc., and each of these registers have to be set as a write cycle in the initial time.

Burst Mode

When the Command Byte is 10111110 (or 10111111), the HT1380/HT1381 is configured in burst mode. In this mode the eight clock/calendar registers can be written (or read) in series, starting with bit 0 of register address 0 (see the timing on the next page).



Test Mode

When the Command Byte is set as 1001xxx1, HT1380/HT1381 is configured in test mode. The test mode is used by Holtek only for testing purposes. If used generally, unpredictable conditions may occur.

Write Protect Register

This register is used to prevent a write operation to any other register. Data can be written into the designated register only if the Write Protect signal (WP) is set to logic 0. The Write Protect Register should be set first be- fore restarting the system or before writing the new data to the system, and it should set as logic 1 in the read cy- cle. The Write Protect bit cannot be written to in the burst mode.

Clock HALT Bit

D7 of the Seconds Register is defined as the Clock Halt Flag (CH).

When this bit is set to logic 1, the clock oscillator is stopped and the chip goes into a low-power standby mode. When this bit is written to logic 0, the clock will start.

12-hour/24-hour Mode

The D7 of the hour register is defined as the 12-hour or 24-hour mode select bit.

When this bit is in high level, the 12-hour mode is se- lected otherwise it s the 24-hour mode.

AM-PM Mode

These are two functions for the D5 of the hour register determined by the value D7 of the same register. One is used in AM/PM selection on the 12-hour mode. When D5 is logic 1, it is PM, otherwise it s AM. The other is used to set the second 10-hour bit (20~23 hours) on the 24-hour mode.

Reset and Serial Clock Control

The REST pin is used to allow ccess data to the shift register like a toggle switch. When the REST pin is takenhigh, the built-in control logic is turned on and the address/command sequence can access the correspond- ing shift register. The REST pin is also used to terminate either single-byte or burst mode data format.

The input signal of SCLK is a sequence of a falling edge followed by a rising edge and it is used to synchronize the register data whether read or write. For data input, the data must be read after the rising edge of SCLK. The data on the I/O pin becomes output mode after the fall- ing edge of the SCLK. All data transfer terminates if the REST pin is low and the I/O pin goes to a high imped-ance state. The data transfer is illustrated on the next page.

Data Input and Data Out

In writing a data byte with HT1380/HT1381, the read/write should first set as R/W=0 in the Command Byte and follow with the corresponding data register on the rising edge of the next eight SCLK cycles. Additional SCLK cycles are ignored. Data inputs are entered start- ing with bit 0.

In reading a data on the register of HT1380/HT1381, R/W=1 should first be entered as input. The data bit out- puts on the falling edge of the next eight SCLK cycles. Note that the first data bit to be transmitted on the first falling edge after the last bit of the read command byte is written. Additional SCLK cycles re-transmits the data bytes as long as REST remains at high level. Data out- puts are read starting with bit 0.



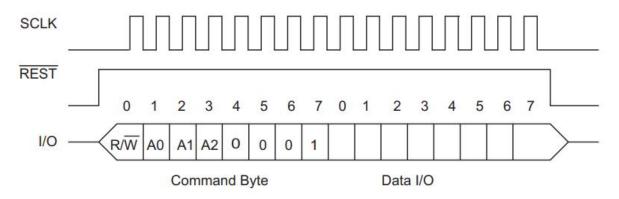
Crystal Selection

A 32768Hz crystal can be directly connected to the HT1380/HT1381 on pins 2 and 3 which are the crystal X1 and X2 pins. In order to ensure that the desired fre- quency is achieved, it is recommended to use a crystal with a capacitance of 9.0pF. It is not recommended that additional load capacitors are connected to the X1 and X2 pins. Refer to the following page for the crystal speci- fications.

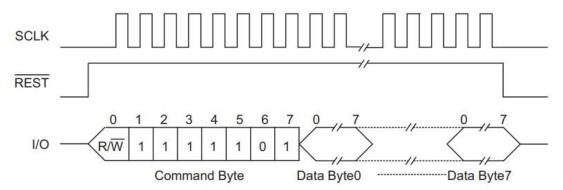


The following diagram shows the single and burst mode transfer:

Single Byte Transfer



Burst Mode Transfer





Crystal Specifications

Symbol	Parameter	Min.	Тур.	Max.	Unit
fo	Nominal Frequency		32.768		kHz
ESR	Series Resistance			50	kΩ
CL	Load Capacitance		9.0		pF

Note: 1. It is strongly recommended to use a crystal with a load capacitance of 9.0 pF. Never use a crystal with a load capacitance of 12.5 pF.

Operating Flowchart

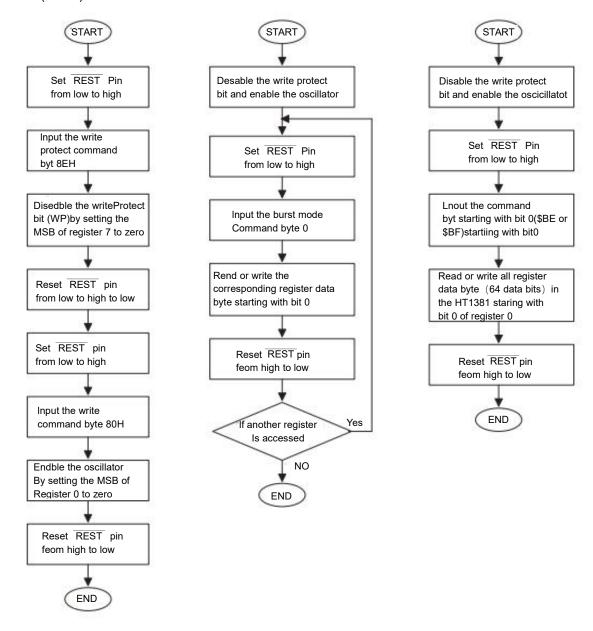
To initiate any transfer of data, REST is taken high and an 8-bit command byte is first loaded into the control logic to pro- vide the register address and command information. Following the command word, the clock/calendar data is serially transferred to or from the corresponding register. The REST pin must be taken low again after the transfer operation is completed. All data enter on the rising edge of SCLK and outputs on the falling edge of SCLK. In total, 16 clock pulses are needed for a single byte mode and 72 for burst mode. Both input and output data starts with bit 0.

In using the HT1380/HT1381, set first the WP and CH to 0 and wait for about 3 seconds, the oscillator will generate the clocks for internal use. Then, choose either single mode or burst mode to input the data. The read or write operating flowcharts are shown on the next page.

^{2.} The oscillator selection can be optimized using a high quality resonator with a small ESR value. Refer to the crystal manufacturer for more details: www.microcrystal.com.



- To disable the write protect (WP=0) bit and enable the oscillator (CH=0)
- Single byte data transfer
- Burst mode data transfer

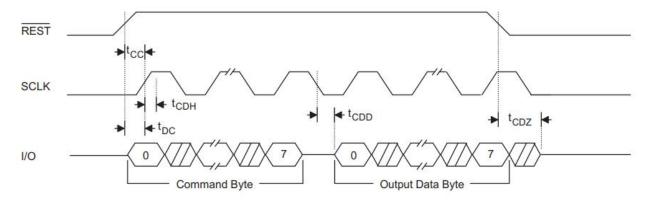


Note:*In reading data byte from HT1380/HT1381 register, the first data bit to be transmitted at the first falling edge after the last bit of the command byte is written.

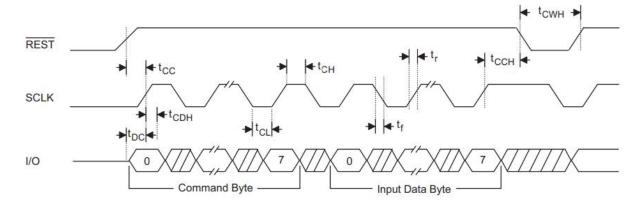


Timing Diagrams

Read Data Transfer

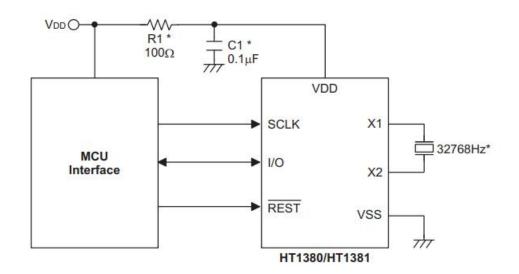


Write Data Transfer





Application Circuits



Note: *

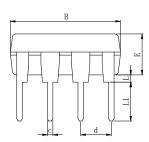
In order to obtain the correct frequency, it is recommended to use a crystal with a load capacitance of 9.0pF. It is not recommended to connect load capacitors to the X1 and X2 pins.

If the power line is noisy, it is recommended to add R1 and C1 for filtering out noise.

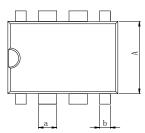


Physical Dimensions

DIP8

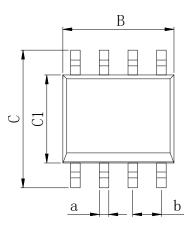


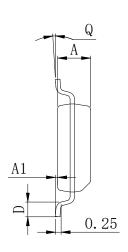




Dimensions In Millimeters(DIP8)											
Symbol:	Α	В	D	D1	Е	L	L1	а	b	С	d
Min:	6.10	9.00	8.40	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54.BSC
Max:	6.68	9.50	9.00	7.82	3.55	0.70	3.60	1.55	0.90	0.50	2.54 BSC

 $SOP8_{\ (150mil)}$





Dimensions In Millimeters(SOP8)									
Symbol:	А	A1	В	С	C1	D	Q	а	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	1.21 BSC



Revision History

DATE	REVISION	PAGE
2014-6-5	New	1-16



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